

# MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material	MF-RX/250
Product Line	Multifuse
Revision Date	August 1, 2005
Revision	A
RoHS Compliant	Yes



No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg. Sn alloy, Cu Copper)	Material/substance weight in grams ( $\pm 0.1\%$ )	CAS No. / Int. Identifier	Material/substance weight %	Sum (%)
1	Epoxy Coating Powder	Epoxy resin	0.1044	25036-25-3	12.51%	12.51%
2	Solder	Sn	0.1070	7440-31-5	12.82%	12.82%
3	Wire	Tin plated Cu	0.1445	-	17.31%	17.31%
4	Foil	Ni plated Cu	0.0622	7505.22-0000	7.45%	7.45%
5	Polymer Compound	HDPE (High Density Polyethylene)	0.2030	9002-88-4	24.32%	43.28%
		Carbon Black	0.1583	1333-86-4	18.96%	
		Additives	0.0554	-	6.64%	

Total Weight (Grams)	0.834800	Total	100%	100%
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